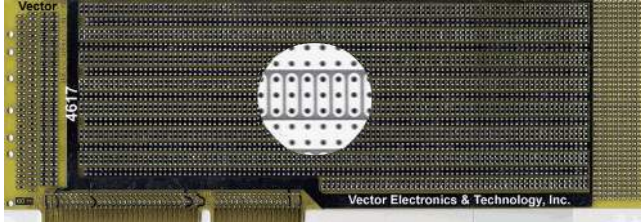


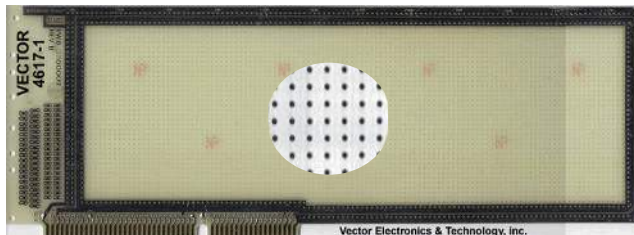
IBM AT/ISA



4617

Circuit Pattern: 3-hole Solder Pad
Contacts: 98 @ .1" Ctrs
 Ni/Gold
Width/Thick: 3.25"/.062"
Height: 4.5"
16-Pin DIP Capacity: 44
Material: FR4 Epoxy Glass
V/G Terminals: T44, T46, T49, T68
Socket Pins: R32
Extender: 3690-26, 3690-26-1
Hole Diameter: .042"

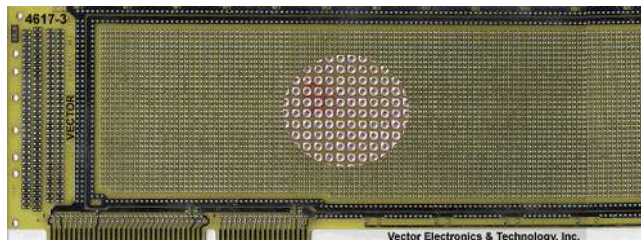
- 0.100" grid
- 3-Hole Solder Pads (0.28" x 0.080" for interconnecting multiple component leads
- 10 x 42 hole grid unrestricted component placement area
- I/O mounting area for up to 70-pin D-subminiature and ribbon cable connectors
- Mounting Bracket and hardware kit included (HD36B)
- Row and column legends provided



4617-1

Circuit Pattern: Peripheral Buses
Contacts: 98 @ .1" Ctrs
 Ni/Gold
Width/Thick: 13.25"/.062"
Height: 4.5"
16-Pin DIP Capacity: 108
Material: FR4 Epoxy Glass
V/G Terminals: T44, T46, T49, T68
Socket Pins: R32
Extender: 3690-26, 3690-26-1
Hole Diameter: .042"

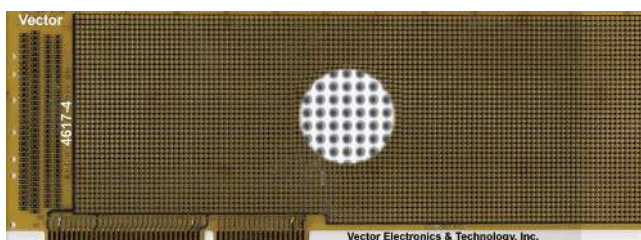
- 0.100" grid
- Bus surfaces solder-coated for convenience
- I/O mounting area for 37-pin D-subminiature and ribbon cable connectors
- Mounting Bracket and hardware kit included (HD36B)
- Row and column legends provided



4617-3

Circuit Pattern: Pad-Per-Hole
Contacts: 98 @ .1" Ctrs
 Ni/Gold
Width/Thick: 13.25"/.062"
Height: 4.5"
16-Pin DIP Capacity: 96
Material: FR4 Epoxy Glass
V/G Terminals: T44, T46, T49, T68
Socket Pins: R32
Extender: 3690-26, 3690-26-1
Hole Diameter: .042"

- 0.100" grid
- Voltage and ground buses around board perimeter
- Pad and bus surfaces solder-coated for convenience
- I/O mounting area for up to 70-pin D-subminiature and ribbon cable connectors
- Mounting Bracket and hardware kit included (HD36B)
- Hole position legend provided, both sides
- Plate thru holes

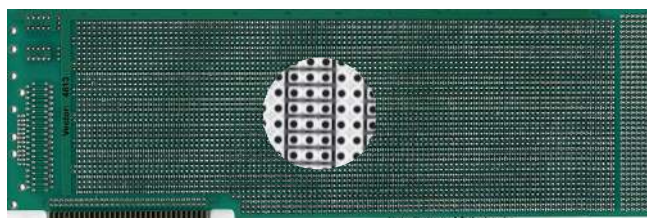


4617-4

Circuit Pattern: Voltage Ground Plane
Contacts: 98 @ .1" Ctrs
 Ni/Gold
Width/Thick: 13.25"/.062"
Height: 4.5"
16-Pin DIP Capacity: 140
Material: FR4 Epoxy Glass
Socket Pins: R50, R51, R52, R53
Extender: 3690-26, 3690-26-1
Hole Diameter: .055"

- 0.100" grid
- Plane surfaces solder-coated for user convenience
- To simulate plated-thru holes committed to voltage or ground planes, use Vector T123 eyelets, available separately (for use without pins)
- Mounting Bracket and hardware kit included (HD36B)
- I/O mounting area for up to 70-pin D-subminiature and ribbon cable connectors

IBM PC, XT



4613

Circuit Pattern: 3-Hole Solder Pad
Contacts: 31/62 @ .1" Ctrs
 Ni/Gold
Width/Thick: 13.25"/.062"
Height: 4.2"
16-Pin DIP Capacity: 93
Material: FR4 Epoxy Glass
V/G Terminals: T44, T46, T49, T68
Socket Pins: R32
Extender: 3690-26
Hole Diameter: .042"

IBM PC, XT

- 0.100" grid
- 3-Hole Solder Pads (0.28" x 0.080" for interconnecting multiple component leads
- I/O mounting area for 37-pin D-subminiature and ribbon cable connectors
- Mounting Bracket and hardware kit included (HD36B)